

C5007

Conductor

Description

C5007 is a wire bondable gold conductor, containing a mixed bonded Au formulation. It has been formulated to be resistant to blistering after multiple firings, also when fired together and Ag/Pd conductor Series of C2000.

Key Features

- Compatible with the recrystallizable HERAEUS dielectrics IP9117 Series Excellent aged wire bond adhesion and contact resistivity properties



This picture does not show the packaging of C5007 and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties

Conductivity	≤ 4.5 milliohms/square (FFT: 12 μm)
Viscosity	30 – 90 Pas (25 °C, D = 75/s)
Alloy Ratio	100
Coverage	c. 50 cm ² / g (FFT: 9 μm)
Metal	Au

Recommended Processing Guide

Printing Parameters	Print through a 200 – 325 mesh screen. Level at room temperature for 10 minutes.
Printing Speed	Up to at least 10 cm / s
Drying Temperature	Dry at 150°C for 10 – 20 minutes.
Process Temperature (TDS)	Fire at 850 °C (peak) for 10 minutes, and with a total firing cycle time of c. 30 – 60 minutes
Film Thickness	6 – 12 μm
Recommended Thinner	HVS 100
Paste Compatibility	Conductors 4 : Print No.1: Ag/Pd C 2000 Series Print No.2: C 5007 Note: The print step No. 1 and 2 can be applied not only on alumina, but also on dielectric IP 9117 Series. Dielectrics: IP 9117 Series IP 9227

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Warranty

6 months

Storage

store in a dry, cool (2 to 23 °C) and dark place with container tightly shut

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